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(54) **PRODUCTION METHOD FOR CIRCUIT BOARD ASSEMBLY**

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(57) **ABSTRACT**

Provided is a method for producing a circuit board assembly, including connecting a lithium ion secondary battery to a circuit board by reflow soldering, wherein the lithium ion secondary battery has been subjected to at least initial charging and discharging, and the lithium ion secondary battery has a state of charge (SOC) of 0 to 29% during reflow soldering.

